



# 2412181608 New Process & Material Qualification for EFM32LG & EFM8SB1 WLCSP Package

**PCN Issue Date:** Dec 18, 2024

**Effective Date:** Mar 24, 2025

**PCN Type:** Assembly

## Description of Change

Silicon Labs is pleased to announce the successful qualification of a new bumping process that includes applying plating Re-distribution layer (RDL) and Under-bump metallurgy for EFM32LG & EFM8SB1 WLCSP package.

This bumping process change was initiated due to supplier BASF End of Life (EOL) announcement of copper etchant surfactant R104-B with production stop on Mar 31, 2024. In addition, certain bumping machines for 8inch wafers have already been phased out by the vendor and factory machinery service is limited (FOI Descum, Msetek PBO coating)

As of the effective date of the PCN, Silicon Labs will fulfill orders with either bumping process material until old inventory depletes.

## Reason for Change

Supply continuity due to current supplier (BASF) EOL of copper etchant surfactant R-104B.

## Impact on Form, Fit, Function, Quality, Reliability

No change to Form, Fit, Function, Quality and Reliability.

## Product Identification

Existing Part #  
EFM32LG360F256G-F-CSP81  
EFM32LG360F256G-F-CSP81R  
EFM8SB10F8G-A-CSP16  
EFM8SB10F8G-A-CSP16R

**Last Date of Unchanged Product:** Mar 24, 2025

## Qualification Samples

Available upon request

## Customer Response

Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change, Ref. JEDEC-J-STD-046.

To request further data or inquire about this notification, please contact your Silicon Labs sales representative. A list of Silicon Labs sales representatives is available at <http://www.silabs.com>.


Customers may approve early PCN acceptance by emailing approval, along with PCN # to [PCN@silabs.com](mailto:PCN@silabs.com)

## User Registration

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## Qualification Data

Attached to this PCN Notification



### EFM32LG360F256G-F-CSP81 New Bumping Qualification Report

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Part Rev A2, TSMC Fabrication, ASECL Assembly except as noted							
Test Name	Test Condition	Qualification	Lot ID or Start	Fail/Pass or End	Notes	Summary	Status
<b>Test Group A – Accelerated Environment Stress Tests - EFM32WG</b>							
uHAST	JA118	3 lots, N=>25	Q051578	0/45	1	3 lots	Pass
	Cond A: 130°C, 85%RH		Q051579	0/46	1		
	96 hours		Q051580	0/44	1		
Temp Cycle	JA104	3 lots, N=>25	Q051575	0/49	1	3 lots	Pass
	Cond C: -65°C to 150°C		Q051576	0/49	1		
	500 cycles		Q051577	0/47	1		
HTSL	JA103	3 lots, N=>25	Q051581	0/50		3 lots	Pass
	150°C, 1000hr		Q051582	0/50			
			Q051583	0/50			

Notes:  
 1. Parts are Pre-conditioned at MSL1/260°C

This report applies to the following part numbers:

EFM32LG360F256G-F-CSP81  
 EFM32LG360F256G-F-CSP81/R

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Prepared on: 2024-12-09 by J. Doe



### EFM8SB10F8G-A-CSP16 New Bumping Qualification Report

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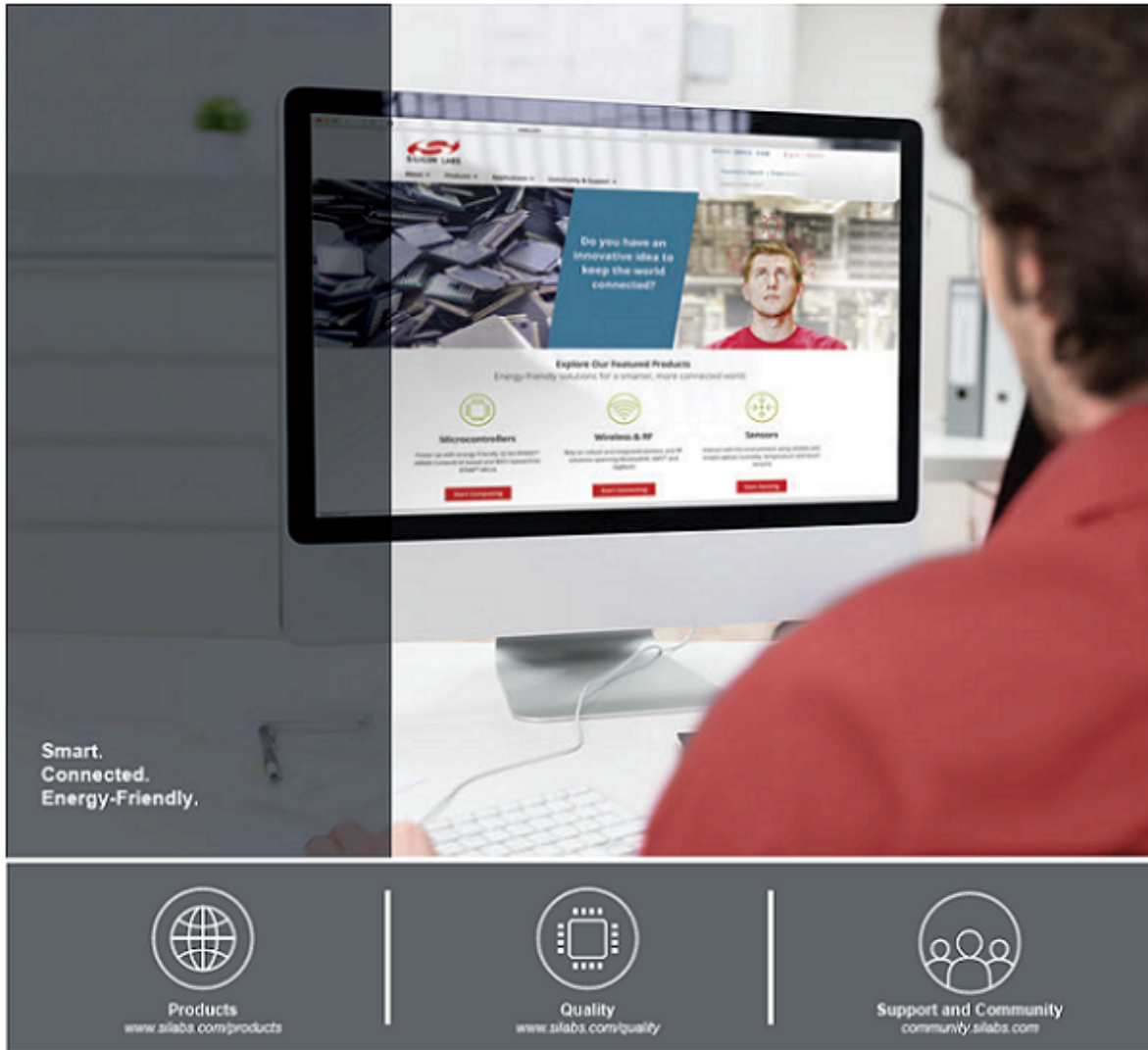
Part Rev C, TSMC Fabrication, ASECL Assembly except as noted								
Test Name	Test Condition	Qualification	Lot ID or Start	Fail/Pass or End	Notes	Summary	Status	
<b>Test Group A – Accelerated Environment Stress Tests - EFM32WG</b>								
uHAST	JA118	3 lots, N=>25	Q051597	0/49	1	3 lots	Pass	
	Cond A: 130°C, 85%RH		Q051598	0/50	1			
	96 hours		Q051599	0/48	1			0/147
Temp Cycle	JA104	3 lots, N=>25	Q051594	0/50	1	3 lots	Pass	
	Cond C: -65°C to 150°C		Q051595	0/50	1			0/150
	500 cycles		Q051596	0/50	1			
HTSL	JA103	3 lots, N=>25	Q051600	0/50		3 lots	Pass	
	150°C, 1000hr		Q051601	0/50				
			Q051602	0/50				0/150

**Notes:**

- Parts are Pre-conditioned at MSL1/260°C

This report applies to the following part numbers:

EFM8SB10F8G-A-CSP16  
 EFM8SB10F8G-A-CSP16R



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